


Standard* Thick Film Ceramic Microwave Resistors

Part Number	Image	Footprint	Frequency (GHz)	Resistance (Ohms)	Power (W)	Return Loss (dB)	Base Material	TCR (ppm/°C)	Style	Resistor Surface	Back Surface	Mount
C1A101050R0J4A0		0404	5	50 ± 5%	1	10	10 mil 96% Alumina	± 200	Top Contact	Au/Sn	---	Solder Attach
R3B100550R0J5G0		0402	5	50 ± 5%	0.5	10	15 mil 96% Alumina	± 300	Single Wrap	Au	Au	Epoxy/ Wire Bondable
R3C131350R0G4K0		0505	12	50 ± 2%	1.25	10	20 mil 96% Alumina	± 200	Single Wrap	Au plate	Au Plate	Epoxy/ Wire Bondable
C1A131350R0G4A2		0505	16	50 ± 2%	1	10	10 mil 96% Alumina	± 200	Top Contact	Au/Sn	---	Solder Attach
R1B131350R0F5BT		0505	16	50 ± 1%	1	10	15 mil 96% Alumina	± 300	Top Contact	Pt-Au/ SN62	---	Solder Attach
R2B131350R0J5J0		0505	16	50 ± 5%	1	10	15 mil 96% Alumina	± 300	Dual Wrap	Sn/Pb over Ni	Sn/Pb over Ni	Solder Attach
R2B131350R0J5L0		0505	16	50 ± 5%	1	10	15 mil 96% Alumina	± 300	Dual Wrap	Pd/Ag	Pd/Ag	Solder Attach
R1A100550R0J5C0		0402	17	50 ± 5%	0.5	10	10 mil 96% Alumina	± 300	Top Contact	Pd/Ag	---	Solder Attach
R1A100550R0J5A0		0402	17	50 ± 5%	0.5	10	10 mil 96% Alumina	± 300	Top Contact	Au	---	Epoxy/ Wire Bondable
C1K131350R0G4F2		0505	17	50 ± 2%	2	10	25 mil BeO	± 200	Top Contact	Au	Pd-Ag	Solder Attach or Epoxy/ Wire Bondable
R2B080550R0J5J0		0302	18	50 ± 5%	0.5	10	15 mil 96% Alumina	± 300	Dual Wrap	Sn/Pb over Ni	Sn/Pb over Ni	Solder Attach
R2B100550R0J5G0		0402	18	50 ± 5%	0.5	10	15 mil 96% Alumina	± 300	Dual Wrap	Au	Au	Epoxy/ Wire Bondable
R2B130850R0J4J0		0503	18	50 ± 5%	0.5	10	15 mil 96% Alumina	± 200	Dual Wrap	Sn/Pb over Ni	Sn/Pb over Ni	Solder Attach
R3A100550R0J5G0		0402	18	50 ± 5%	0.5	10	10 mil 96% Alumina	± 300	Single Wrap	Au	Au	Epoxy/ Wire Bondable
C3A110650R0K5K5		0402	20	50 ± 10%	1	10	10 mil 96% Alumina	± 300	Single Wrap	Au/Ni	Au /Ni	Epoxy/ Wire Bondable
R1A060350R0G5AR		0201	20	50 ± 2%	0.25	10	10 mil 96% Alumina	± 300	Top Contact	Au/Sn	---	Solder Attach

* Custom options also available upon request